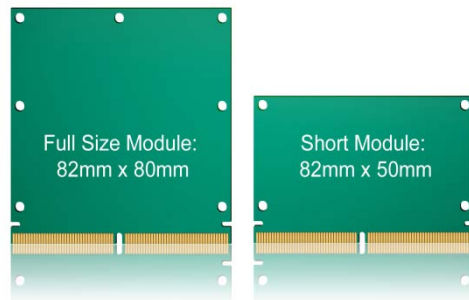


ULP COM

Ultra Low Power Computer on Module
for ARM or SOC

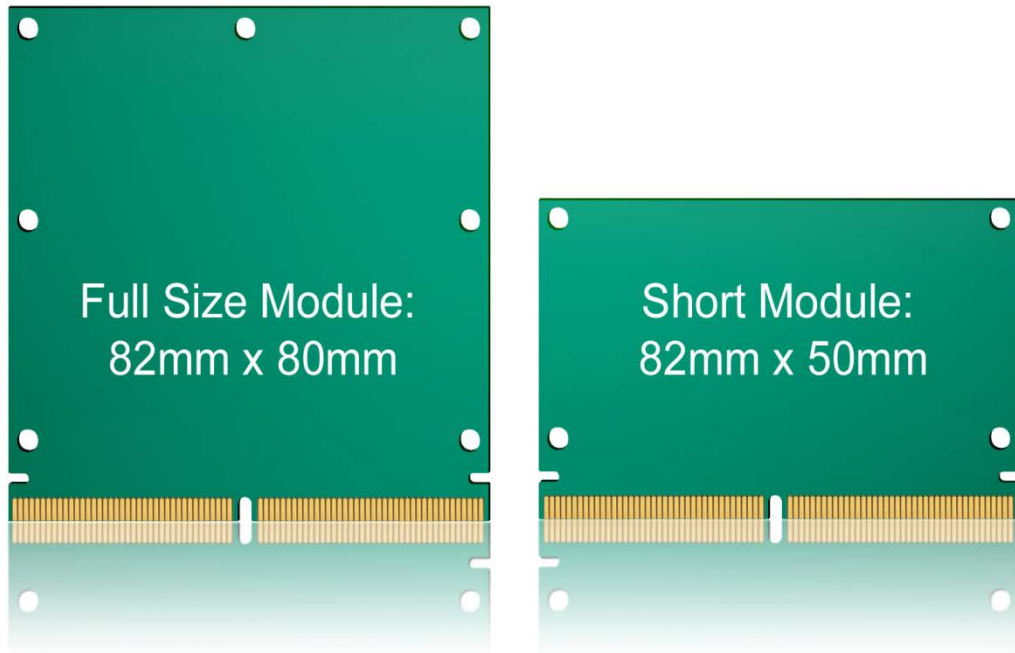


Sizes : 82 x 50mm or 82 x 80 mm

Announcement of on COM

- **Cooperation between ADLink and Kontron**
- **Processor targets : ARM/RISC & SOC**
- **Module Sizes : short 82x50 mm or full 82x80 mm**
- **Connector : 314-pin MXM 3.0 connector**
- **Display support : RGB, LVDS, HDMI, Displayport**
- **OS Support : Linux, Android, Windows CE, Windows 8, VxWorks and QNX.**

Module sizes

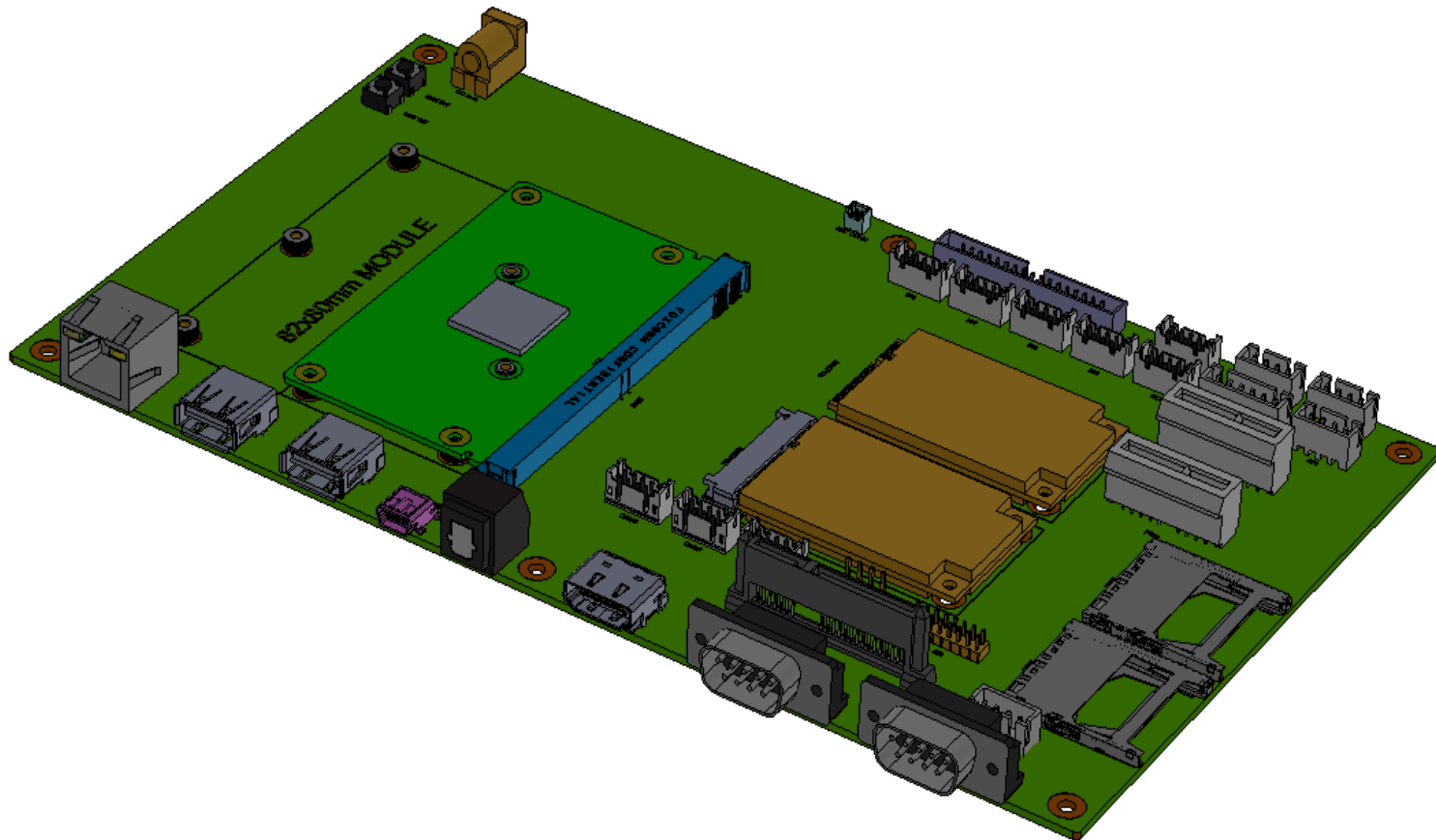


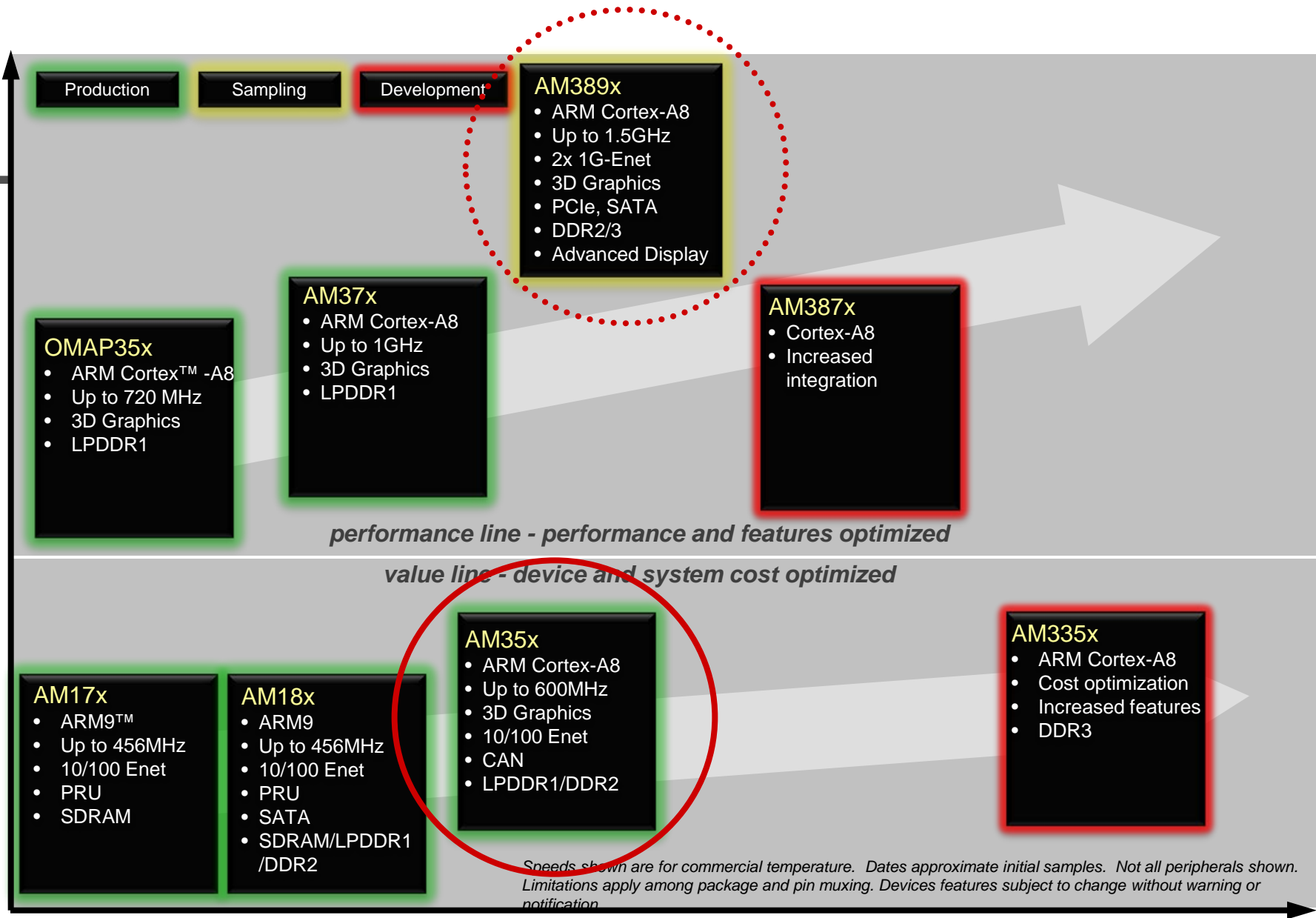
314-pin MXM 3.0 connector

Functions on connector

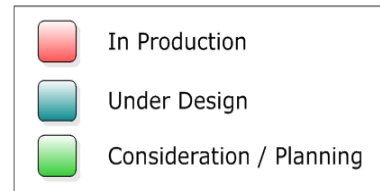
- 24-bit RGB
- 24-bit LVDS
- HDMI
- Displayport
- PCIe
- SATA
- USB
- USB OTG
- Gigabit LAN
- SDIO/eMMC
- Camera IN (Par / Ser)
- UART
- CAN bus
- SPI
- i2C / I2S
- GPIO


Module with Carrier






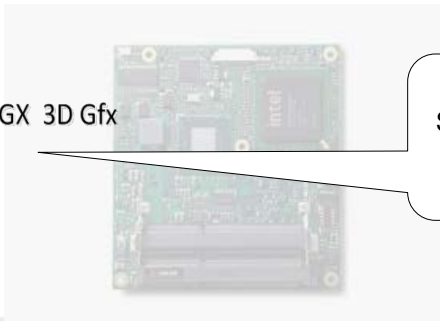
ARM / SOC Roadmap (subject to change)



 **ASCOM-T3**
NVIDIA® Tegra® 3 with Quad Cortex-A9 at 1.3 Ghz
1 GB DDR3, PCIe, SATA, HDMI, GbE

 **ASCOM-387x**
TI Sitara AM3874 up 1.5 GHz + PowerVR SGX530 3D Gfx
1 GB DDR3, PCIe, SATA, HDMI, GbE

 **ASCOM-3517**
ARM Cortex 8 up 1 GHz + PowerVR SGX 3D Gfx
512 MB DDR2, HDMI, GbE



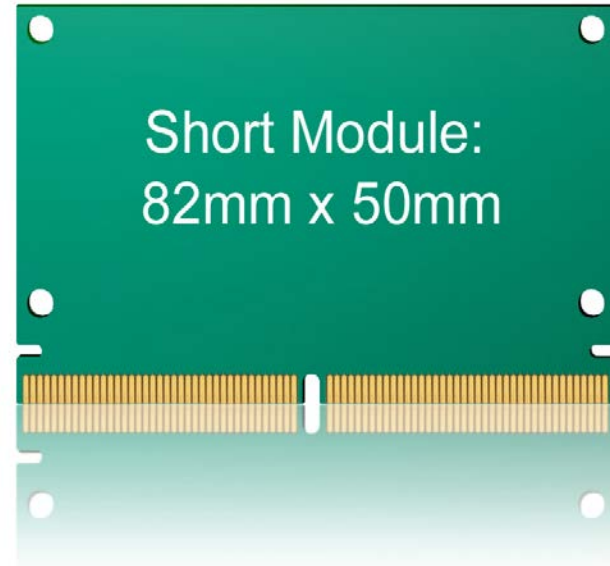
Started, early samples
June 2012

COM 
Express

 **ADLINK**
TECHNOLOGY INC.

ASCOM-3517

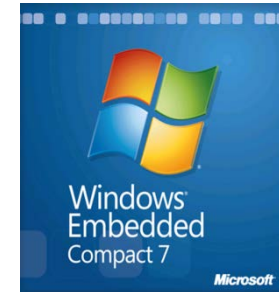
- **AM3517/05 Sitara ARM Microprocessor:**
 - MPU Subsystem
 - 600-Mhz Sitara™ ARM® Cortex-A8™ Core
 - NEON SIMD Coprocessor and Vector floating point (FP) co-proc
- **Memory**
 - 256 or 512 MB DDR2 SDRAM
 - 128 or 256 MB NAND Flash (x8)
 - 256KB EEPROM
- **Video**
 - LCD 24-bit RGB + control and I2C
 - Camera 8-bit with I2C
- **System Busses**
 - 3x I2C, 4x I2S, 12 GPIO, 2x SPI
- **Communcation**
 - Four RS232 + one High-End CAN 10/100 Mbit Ethernet MAC
 - One USB Host and one USB Host/OTG
 - LAN 10/100 Mbps MAC/PHY
- **Off module storage support**
 - One SDIO 4-bit, one MMC 8-bit
- **Embedded Features**
 - Boot Selector, JTAG
- **Power Input** : single 3.3 ~ 5V
- **Mechanical** : short 82x50mm with 314-pin MXM 3.0 golden finger



BSP Support

- Microsoft Windows

- Windows CE7.0 (WEC7)
- Windows CE6.0



- Linux

- Android (rev TBD)
- Standard Distribution



- Realtime

- VxWorks
- QNX



Company wide IP model for ARM

IP Level



BSP Level



Application Level

- Hardware IP block (module)
- Software IP (Bootloader / Linux Kernel)
 - Linux Kernel development (back to kernel.org)

- Second Level
 - BSP (winCE, Android, Vxworks, QNX, ..)



- Application (department) using either module + software IP or hardware IP + software IP
- Customers for modules